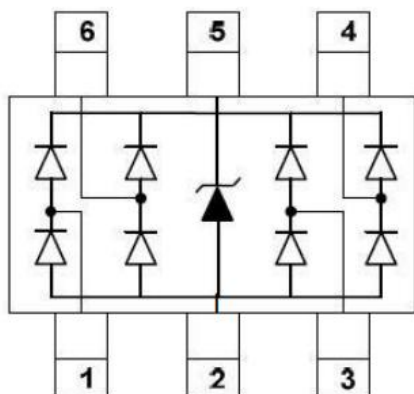


Features

- Junction capacitance (Max value: 0.8pF)
- Peak Pulse current (8/20μs) Max:5A
- IEC61000-4-2 (ESD) ±25kV (air), ±20kV (contact)
- Low clamping voltage
- Low leakage current
- Working voltages:5V
- RoHS Compliant

Appearance & Symbo



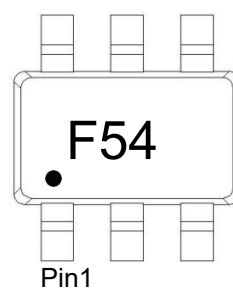
Circuit and Pin Schematic

Mechanica Characteristics

- Package: SOT-363
- Lead Finish:Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Tape Reel :3000pcs

Applications

- Peripherals
- Industrial Equipment
- Notebook Computers
- Portable Instrumentation
- Microprocessor Based Equipment
- Cell Phone Handsets and Accessories
- Personal Digital Assistants (PDAs) and Pagers



F54=Marking Code

Absolute Maximum Ratings (T=25°C, RH=45%-75%, unless otherwi

Parameters	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P _{PP}	75	W
Peak Pulse Current (8/20μs)	I _{PP}	5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±25 ±20	KV
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Electrical Characteristics (T=25°C, RH=45%-75%, unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}				5	V
Reverse Breakdown Voltage	V _{BR}	I _R = 1mA	6		9	V
Reverse Leakage Current	I _R	V _R = 5V			0.5	μA
Clamping voltage	V _C	I _{PP} = 1A, T _P =8/20us			10	V
Clamping voltage	V _C	I _{PP} = 5A, T _P =8/20us			15	V
Junction capacitance	C _J	V _R =0V, f =1MHz, between I/O pins		0.3	0.4	pF
Junction capacitance	C _J	V _R =0V, f =1MHz, any I/O to ground			0.8	pF

FIG1: Power rating derating curve

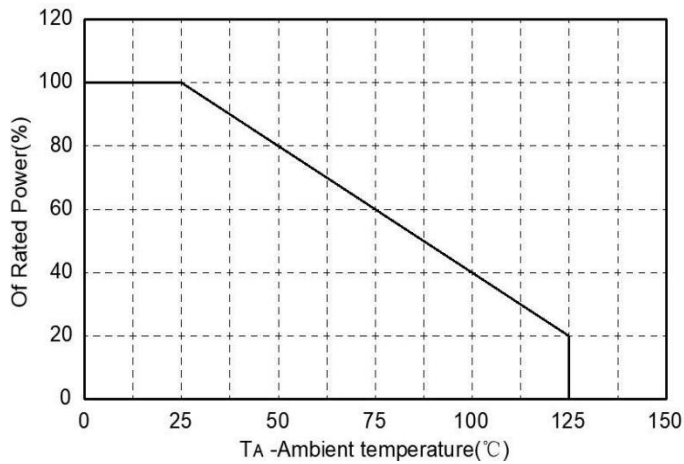


FIG2: pulse Waveform

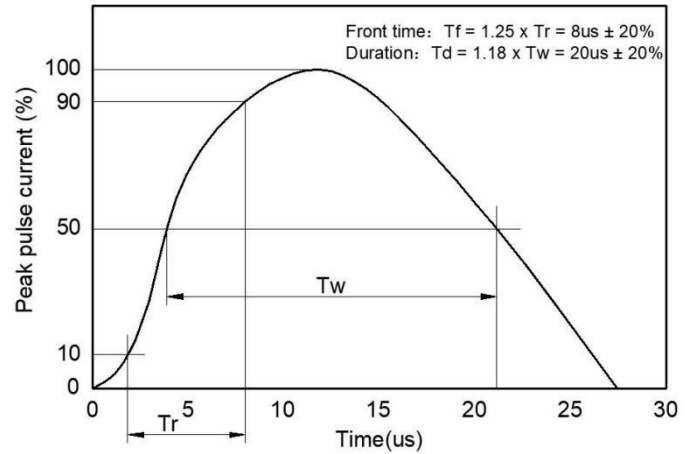


FIG3: Capacitance between terminals characteristics

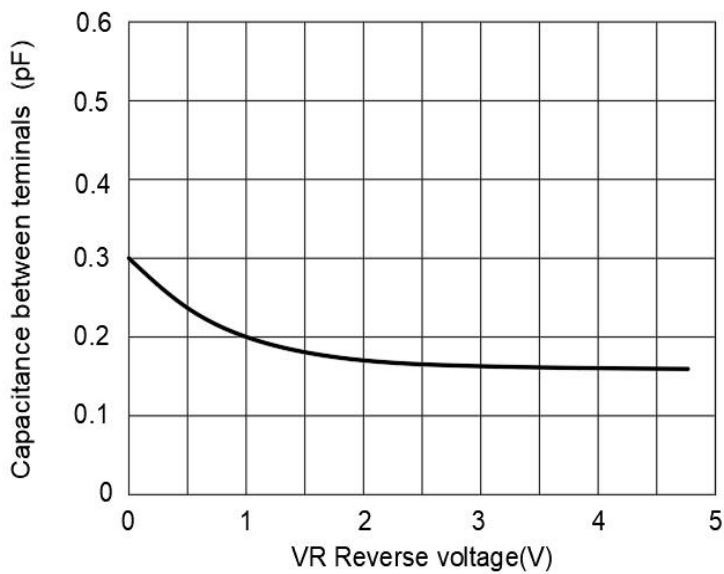
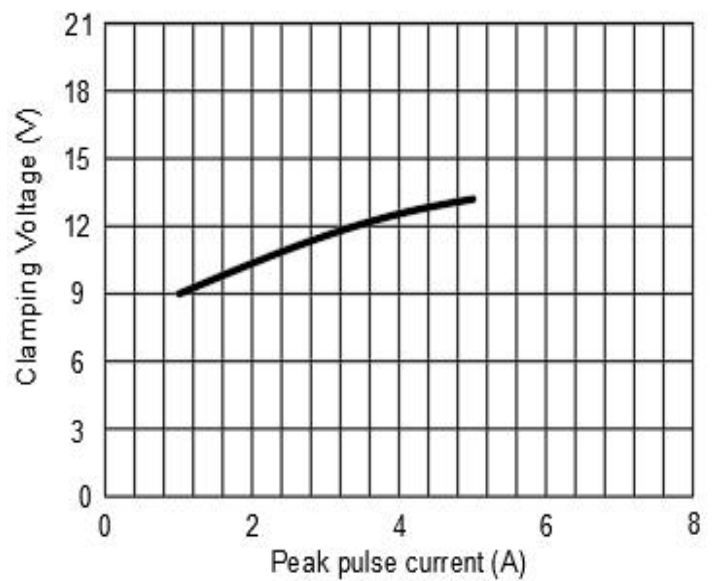
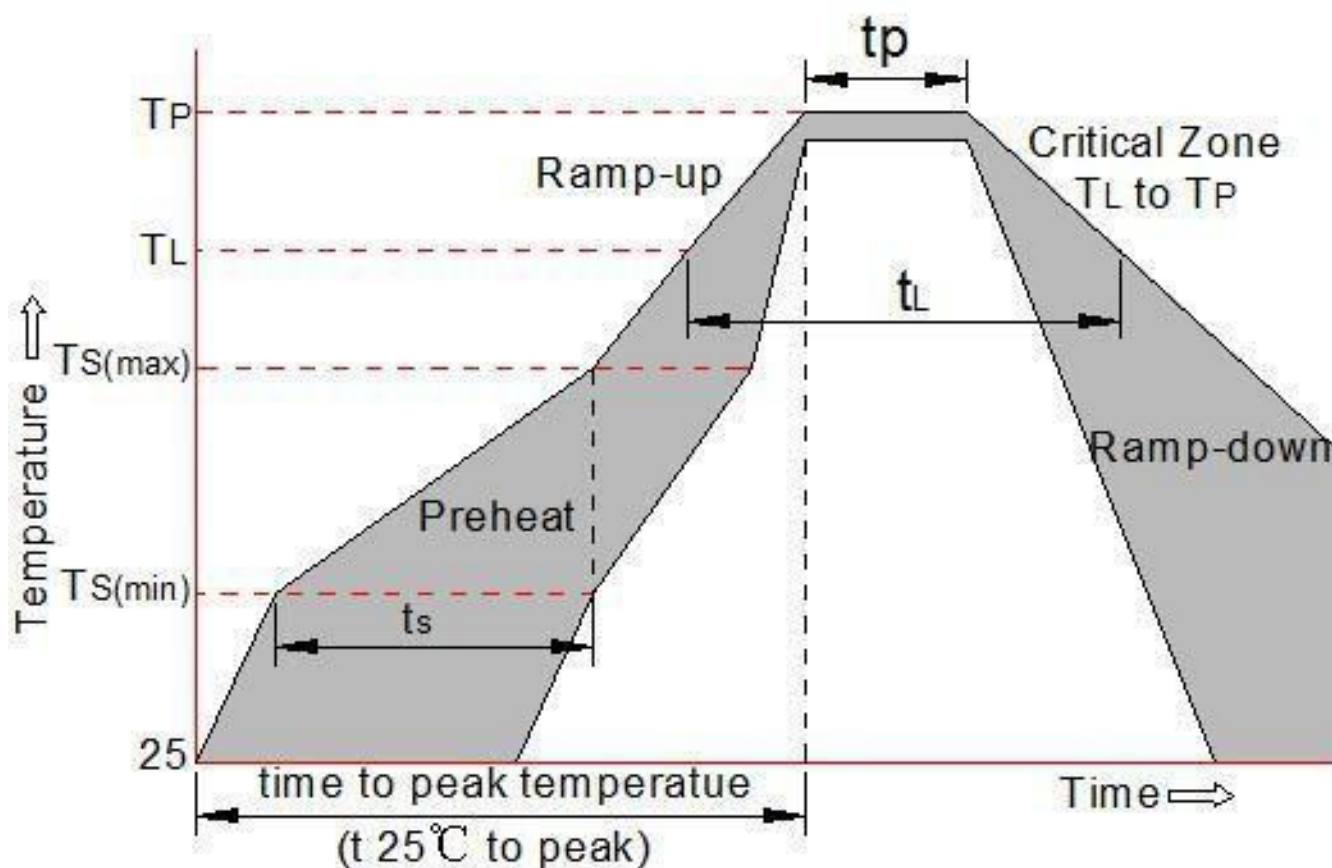


FIG4: Clamping Voltage vs. Peak Pulse Current

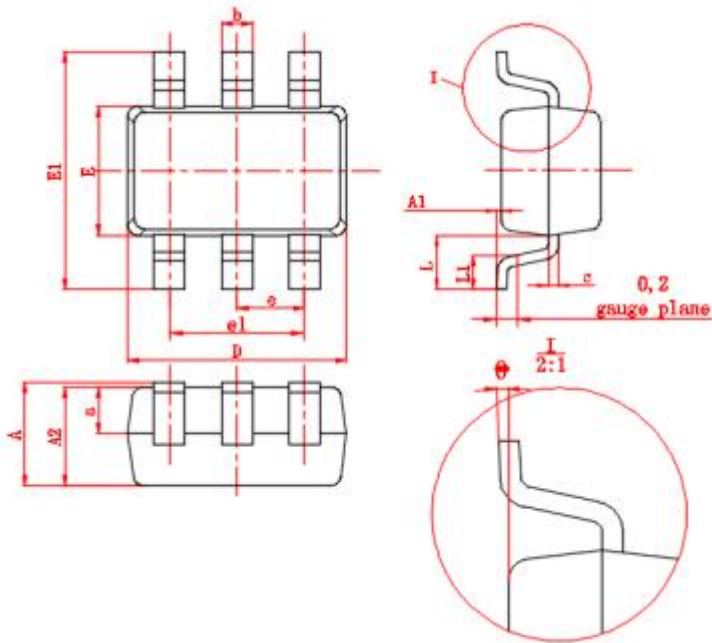


Soldering parameters

Reflow Condition		Pb-Free assembly see as bellow
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

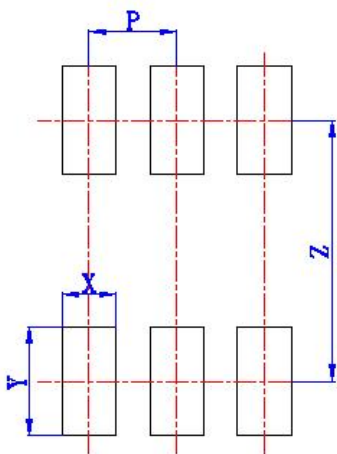


Package mechanical data



Symbol	Dimension in Millimeters	
	min	max
A	0.9	1.1
A1	0	0.1
A2	0.9	1.0
a	(0.45)	
D	2.0	2.2
E	1.15	1.35
E1	2.15	2.45
e	(0.65)	
e1	1.2	1.4
b	0.25	0.35
c	0.08	0.15
L	(0.525)	
L1	0.26	0.46
θ	0°	8°

Suggested Land Pattern



Symbol	Dimension in Millimeters	
	typ	
X	(0.4)	
Y	(0.8)	
Z	(1.8)	
P	(0.65)	